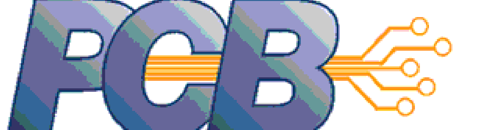

Printed Circuit Boards
Interconnection Carriers

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
08	198	FR4	35	L20.35 L50.35	P10	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_198_FR4_35_L20.35_L50.35_p10

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	B
	100µ	Prepreg		B
Layer-2	35µ	Copper		A1, B
	200µ	L-FR4		A1, B
Layer-3	35µ	Copper		A1, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-4	35µ	Copper		A2, B
	500µ	L-FR4		A2, B
Layer-5	35µ	Copper		A2, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-6	35µ	Copper		A3, B
	200µ	L-FR4		A3, B
Layer-7	35µ	Copper		A3, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-99	35µ	Copper		B

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